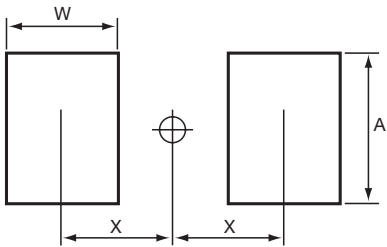


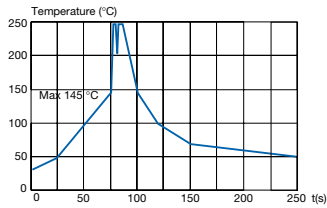
SOLDERING OF SMD CAPACITORS

The Evox Rifa SMD capacitors can be soldered on printed boards either by Reflow soldering, Vapour phase soldering (not the MMC) or Wave soldering. Please see below the recommended soldering profiles for Reflow and Wave soldering.
The recommended soldering land dimensions are:

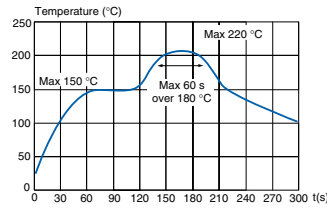
L mm	Case size		W		Ah		Av		X	
	Horizontal	Vertical	mils	mm	mils	mm	mils	mm	mils	mm
5.7	2220 - J31, J91		60	1.5	200	5.1			118.58	3.0
5.7	2220 - J33, J93		60	1.5	200	5.1			118.58	3.0
5.7	2220 - J35, J95		60	1.5	200	5.1			118.58	3.0
7.3	2824 - K31, K91		60	1.5	240	6.1			148.11	3.8
7.3	2824 - K33, K93		60	1.5	240	6.1			148.11	3.8
7.3	2824 - K35, K95		60	1.5	240	6.1			148.11	3.8
7.3	2824 - K37, K97		60	1.5	240	6.1			148.11	3.8
10.2	4036 - A31	4022 - A31V	80	2.0	360	9.1	220	5.6	217.15	5.5
12.7	5045 - B31	5026 - B31V	100	2.5	455	11.6	260	6.6	276.4	7.0
16.5	6560 - C31	6528 - C31V	120	3.0	590	15.0	280	7.1	355.3	9.0



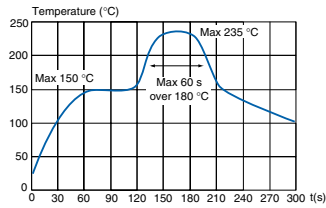
Ah = horizontal mounting
 Av = vertical mounting



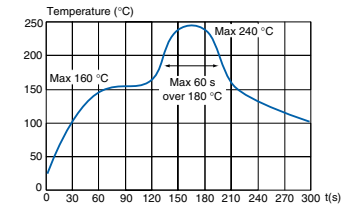
Recommended wave soldering profile for all Evox Rifa SMD capacitors, totaltime in solder wave < 5s.



Recommended reflow soldering profile for MMC



Recommended reflow soldering profile for GMC and GPC



Recommended reflow soldering profile for SMC and SPC

The recommended solder paste thickness for the **naked SMD** (SMW, GMW) parts is at least 0.15 mm (6 mils), for thicknesses below 0.15 mm (6 mils) please consult Evox Rifa.

MARKING OF SMD CAPACITORS

The nominal **capacitance value** is given with 3 digits EIA-code,

Examples: 103 = 10000 pF = 10 nF = 0.01 μF

The **capacitance tolerance** is expressed with letter codes:

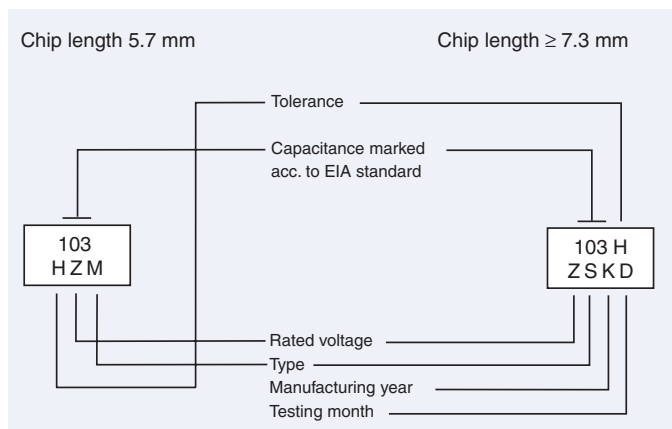
M	± 20 %	H	± 2.5 %
K	± 10 %	G	± 2 %
J	± 5 %	F	± 1 %

The **rated voltage** is expressed with letter codes:

Z	50 VDC	H	250 VDC
C	63 VDC	K	400 VDC
D	100 VDC	M	630 VDC
F	160 VDC	P	1000 VDC
W	1200 VDC		

The **capacitor type** codes are as follows:

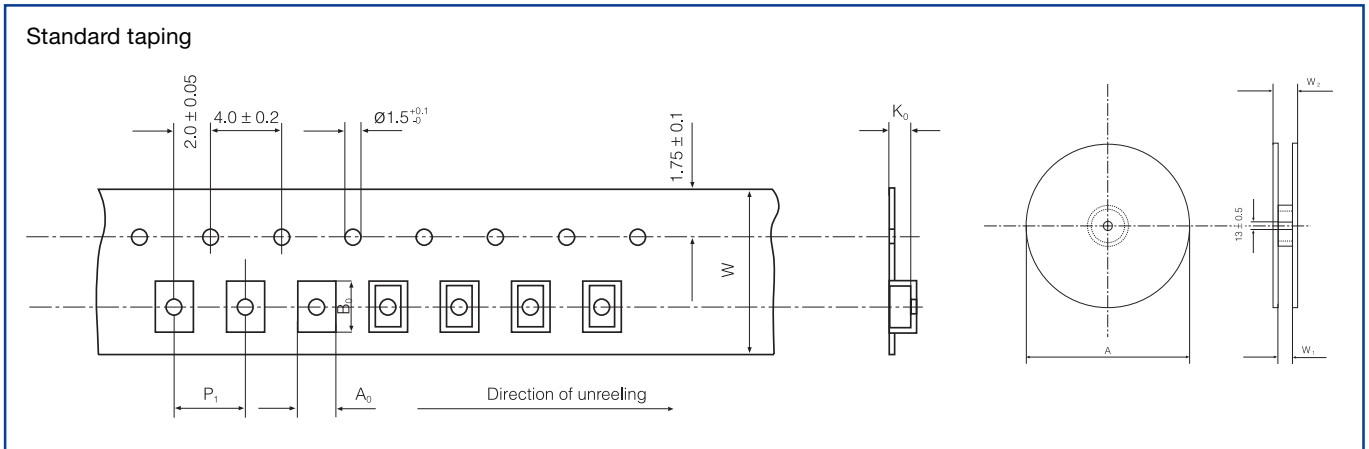
M	MMC	P	GPC
S	SMC, SMW	D	SPC
G	GMC, GMW		



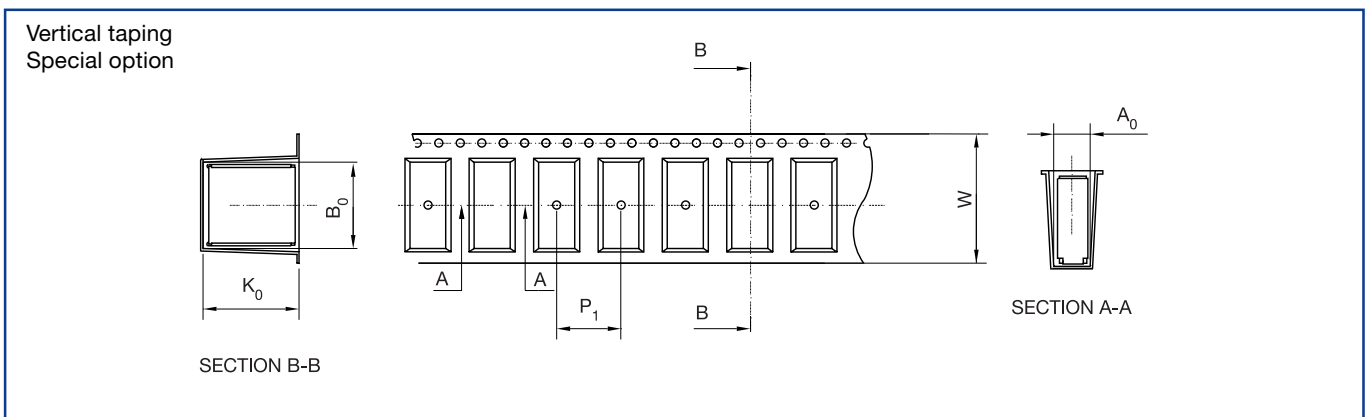
The **manufacturing year** and the **testing month** are expressed according to IEC 60062, see table on page 21.

TAPE PACKAGING OF SMD CAPACITORS

According to IEC 60286-3
Carrier Tape



EIA size code, horizontal mounting	Size of capacitor, mm				$W_{-0.0}^{+0.3}$	$P_1 \pm 0.1$	A_0	B_0	K_0	$A \pm 2.0$	$W_1_{-0}^{+2}$	$W_2 \text{ max}$	Qty/pcs
	L	B	H	W									
2220	5.7	5.0	2.5	12.0	8.0	5.5	6.0	2.8	330	12.4	22.0	3100	
2220	5.7	5.0	3.0	12.0	8.0	5.5	6.0	3.3	330	12.4	22.0	2400	
2220	5.7	5.0	4.0	12.0	8.0	5.5	6.0	4.3	330	12.4	22.0	2100	
2824	7.3	6.0	2.5	12.0	8.0	6.5	7.5	2.8	330	12.4	22.0	3100	
2824	7.3	6.0	3.0	12.0	8.0	6.5	7.5	3.3	330	12.4	22.0	2500	
2824	7.3	6.0	3.5	12.0	8.0	6.5	7.5	3.8	330	12.4	22.0	2300	
2824	7.3	6.0	4.5	12.0	8.0	6.5	7.5	4.8	330	12.4	22.0	1700	
4036	10.2	9.1	5.5	16.0	16.0	9.5	10.5	5.8	330	16.4	22.0	800	
5045	12.7	11.5	6.5	24.0	16.0	11.9	13.1	6.8	330	24.4	30.0	600	
6560	16.5	15.0	7.0	24.0	20.0	15.4	16.8	7.3	330	24.4	30.0	500	



EIA size code, vertical mounting	Size of capacitor, mm				$W_{-0.0}^{+0.3}$	$P_1 \pm 0.1$	A_0	B_0	K_0	$A \pm 2.0$	$W_1_{-0}^{+2}$	$W_2 \text{ max}$	Qty/pcs
	L	B*	H*	W									
4022	10.2	5.5	9.1	24.0	16.0	6.0	10.5	9.3	330	24.4	30.0	500	
5026	12.7	6.5	11.5	24.0	16.0	6.9	13.1	11.8	330	24.4	30.0	400	
6528	16.5	7.0	15.0	44.0	20.0	7.5	17.0	15.3	330	44.5	49.5	200	

* Dimensions B and H in vertical mounting correspond H and B in the standard mounting and in the article tables.